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2SA2080

Silicon PNP Epitaxial



ADE-208-1476 (Z)

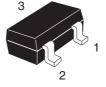
Rev. 0 Feb. 2002

Features

• Low frequency amplifier

Outline

CMPAK



- 1. Emitter
- 2. Base
- 3. Collector

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Collector to base voltage	V _{CBO}	-30	V	
Collector to emitter voltage	V _{CEO}	-30	V	
Emitter to base voltage	V _{EBO}	- 5	V	
Collector current	I _c	-100	mA	
Emitter current	I _E	100	mA	
Collector power dissipation	P _c *	150	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +125	°C	

^{*}Value on the glass epoxy board (10 mm x 10 mm x 0.7 mm)

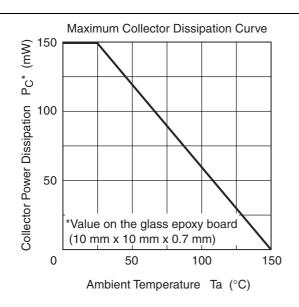
Electrical Characteristics

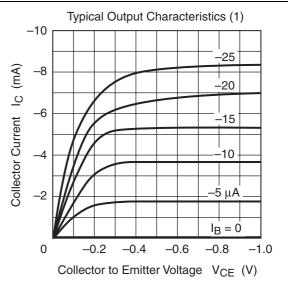
 $(Ta = 25^{\circ}C)$

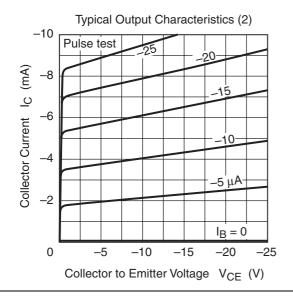
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{_{(BR)CBO}}$	-30	_	_	V	$I_{c} = -10 \mu A, I_{e} = 0$
Collector to emitter breakdown voltage	$V_{_{(BR)CEO}}$	-30	_	_	V	$I_{\rm c} = -1$ mA, $R_{\rm BE} = \infty$
Emitter to base breakdown voltage	$V_{\scriptscriptstyle (BR)EBO}$	- 5	_	_	V	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	-0.5	μΑ	$V_{CB} = -20 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	-0.5	μΑ	$V_{EB} = -2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	100	_	500	_	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$
Collector to emitter saturation voltage	V _{CE(sat)}	_	_	-0.2	V	$I_{c} = -10 \text{ mA}, I_{B} = -1 \text{ mA}$
Base to emitter voltage	V _{BE}	_	_	-0.75	V	$V_{CE} = -12 \text{ V}, I_{C} = -2 \text{ mA}$

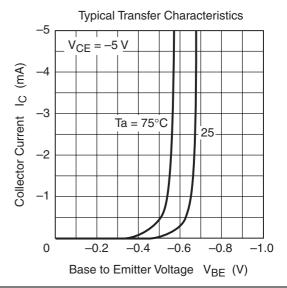
Notes: 1. The 2SA2080 is grouped by h_{FE} as follows.

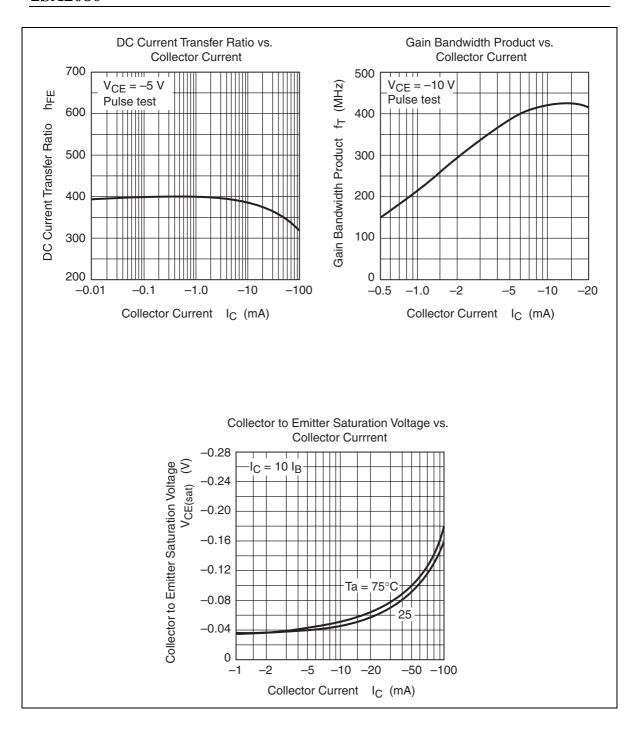
Grade	В	С	D
Mark	МВ	MC	MD
h _{FE}	100 to 200	160 to 320	250 to 500



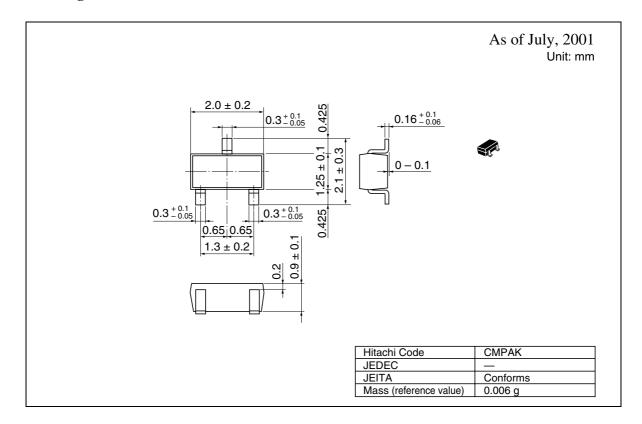








Package Dimensions



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